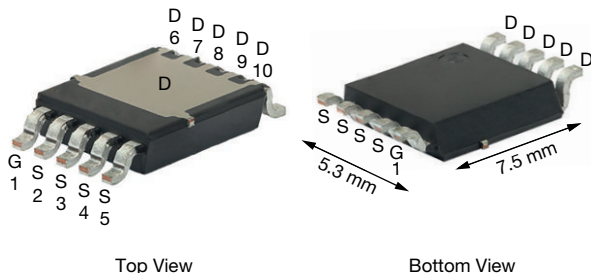


Automotive N-Channel 40 V (D-S) 175 °C MOSFET

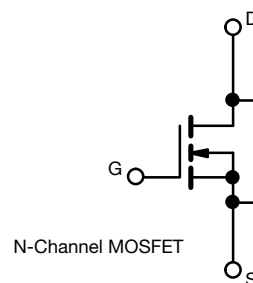
PowerPAK® SO-10LR


FEATURES

- TrenchFET® Gen IV power MOSFET
- AEC-Q101 qualified
- 100 % R_g and UIS tested
- Q_{gd}/Q_{gs} ratio < 1 optimizes switching characteristics
- Material categorization:
for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE



PRODUCT SUMMARY	
V_{DS} (V)	40
$R_{DS(on)}$ (Ω) at $V_{GS} = 10$ V	0.00106
$R_{DS(on)}$ (Ω) at $V_{GS} = 4.5$ V	0.00142
I_D (A) ^d	396
Configuration	Single

ORDERING INFORMATION	
Package	PowerPAK SO-10LR
Lead (Pb)-free and halogen-free	SQJ134ELR (for detailed order number please see www.vishay.com/doc?79776)

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	40	V
Gate-source voltage		V _{GS}	± 20	
Continuous drain current ^d	T _C = 25 °C	I _D	396	A
	T _C = 125 °C		229	
Continuous source current (diode conduction) ^d		I _S	290	
Pulsed drain current ^d		I _{DM}	889	
Single pulse avalanche current	L = 0.1 mH	I _{AS}	61	
Single pulse avalanche energy		E _{AS}	186	mJ
Maximum power dissipation	T _C = 25 °C	P _D	319	W
	T _C = 125 °C		106	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C
Soldering recommendations (peak temperature) ^b			260	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient °	PCB mount a	R _{thJA}	42	°C/W
Junction-to-case (drain)		R _{thJC}	0.5	

Notes

- When mounted on 1" square PCB (FR4 material)
- See solder profile (www.vishay.com/doc?73257). The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Using thermal characterization methods based on JESD51-14
- Values based on R_{thJC} and T_C of 25 °C. Actual values achievable will be dependent on the thermal characteristics of the complete system



SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0, I _D = 250 μA		40	-	-	V
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		1.2	1.7	2.2	
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V		-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 40 V	-	-	10	μA
		V _{GS} = 0 V	V _{DS} = 40 V, T _J = 125 °C	-	-	50	
		V _{GS} = 0 V	V _{DS} = 40 V, T _J = 175 °C	-	-	250	
On-state drain current ^a	I _{D(on)}	V _{GS} = 10 V	V _{DS} ≥ 5 V	30	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 15 A	-	0.00082	0.00106	Ω
		V _{GS} = 4.5 V	I _D = 15 A	-	0.00114	0.00142	Ω
		V _{GS} = 10 V	I _D = 15 A, T _J = 125 °C	-	-	0.0018	
		V _{GS} = 10 V	I _D = 15 A, T _J = 175 °C	-	-	0.0021	
Forward transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 60 A		-	135	-	S
Dynamic ^b							
Input capacitance	C _{iss}	V _{GS} = 0 V	V _{DS} = 25 V, f = 1 MHz	-	7981	11 174	pF
Output capacitance	C _{oss}			-	2105	2947	
Reverse transfer capacitance	C _{rss}			-	137	192	
Total gate charge ^c	Q _g	V _{GS} = 10 V	V _{DS} = 20 V, I _D = 40 A	-	131	197	nC
Gate-source charge ^c	Q _{gs}			-	28	-	
Gate-drain charge ^c	Q _{gd}			-	20	-	
Gate resistance	R _g	f = 1 MHz		0.3	1.2	2.3	Ω
Turn-on delay time ^c	t _{d(on)}	V _{DD} = 20 V, R _L = 0.5 Ω I _D ≅ 40 A, V _{GEN} = 10 V, R _g = 1 Ω		-	17	26	ns
Rise time ^c	t _r			-	9	14	
Turn-off delay time ^c	t _{d(off)}			-	54	81	
Fall time ^c	t _f			-	12	18	
Source-Drain Diode Ratings and Characteristics ^b							
Pulsed current ^a	I _{SM}			-	-	889	A
Forward voltage	V _{SD}	I _F = 15 A, V _{GS} = 0 V		-	-	1.1	V
Body diode reverse recovery time	t _{rr}	I _F = 10 A, di/dt = 100 A/μs		-	67	134	ns
Body diode reverse recovery charge	Q _{rr}			-	121	242	nC
Reverse recovery fall time	t _a			-	40	-	ns
Reverse recovery rise time	t _b			-	28	-	
Body diode peak reverse recovery current	I _{RM(REC)}			-	-3.1	-	A

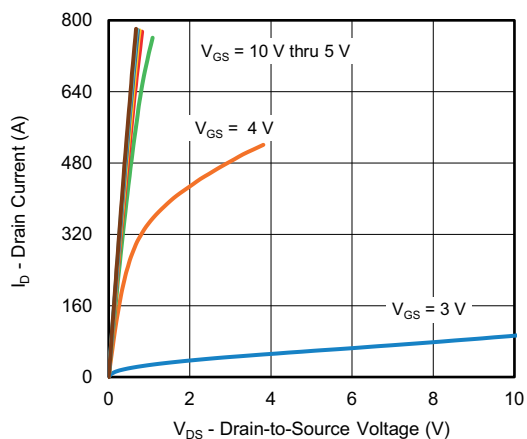
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing
c. Independent of operating temperature

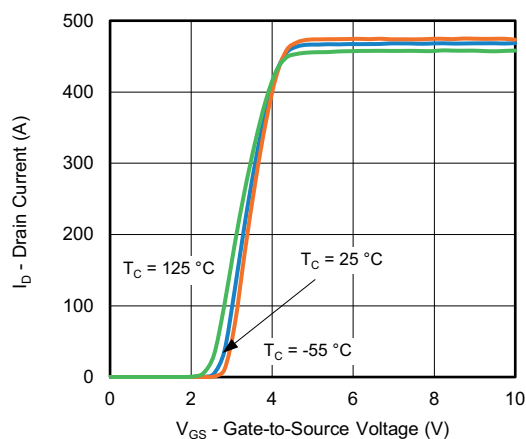
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



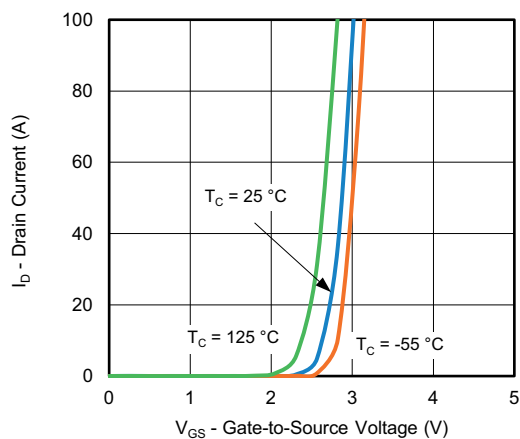
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



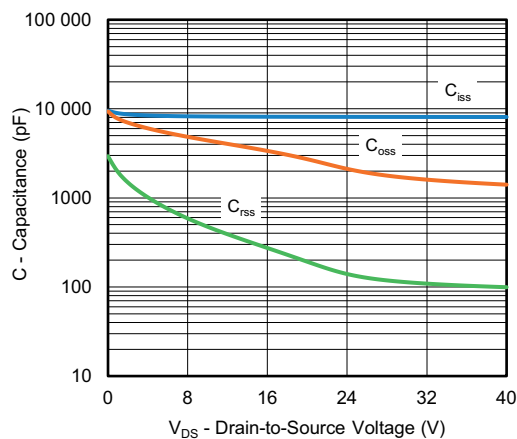
Output Characteristics



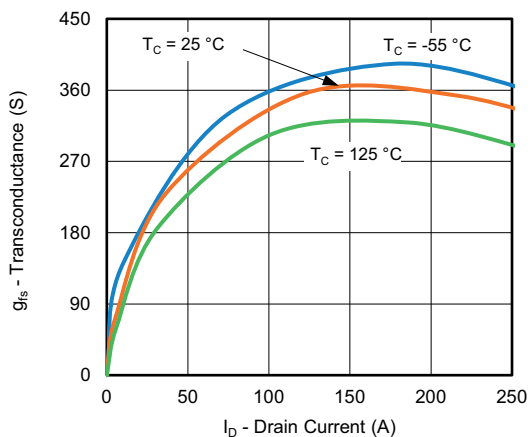
Transfer Characteristics



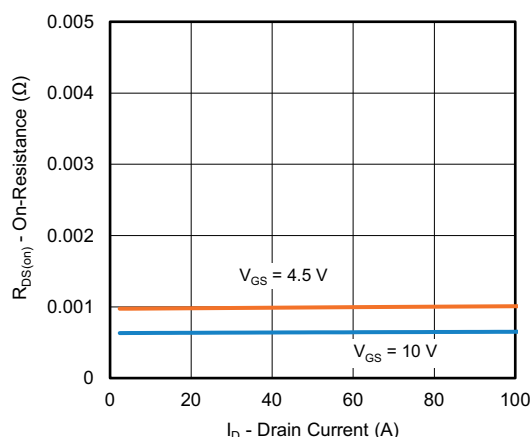
Transfer Characteristics



Capacitance



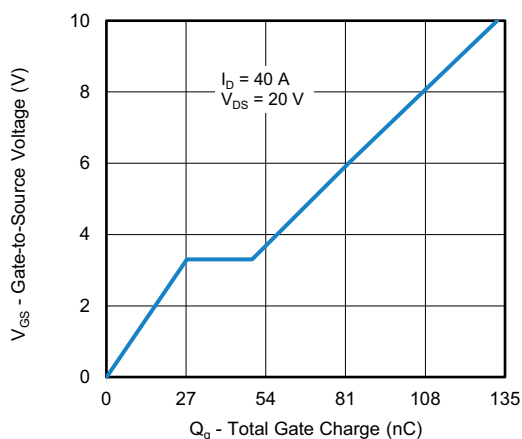
Transconductance



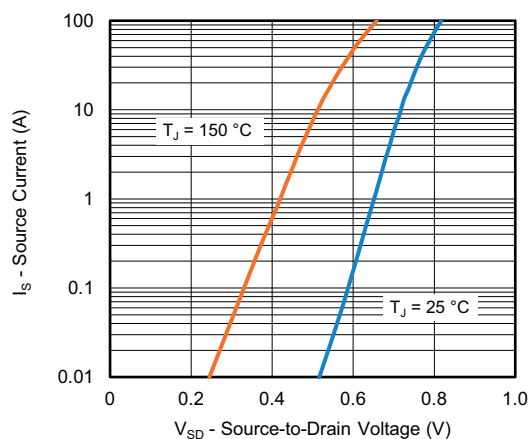
On-Resistance vs. Drain Current



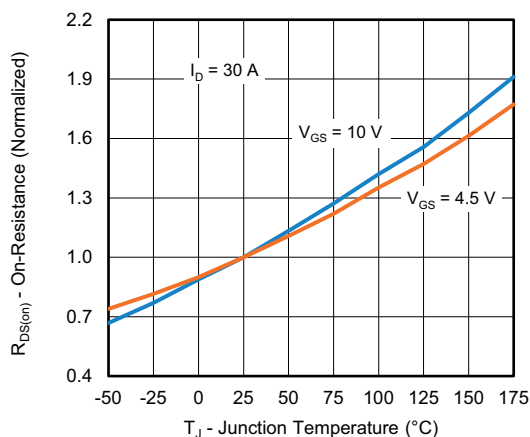
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



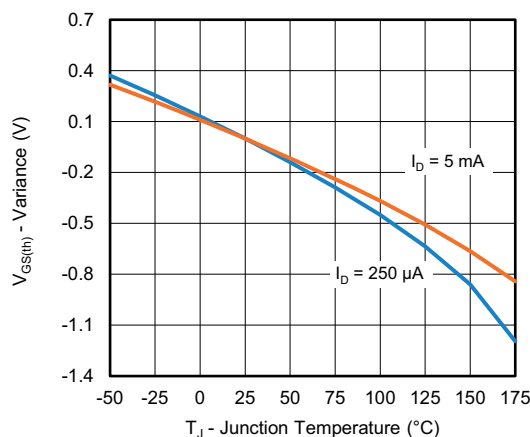
Gate Charge



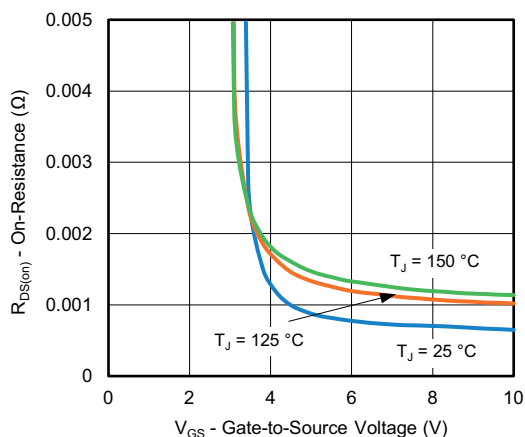
Source Drain Diode Forward Voltage



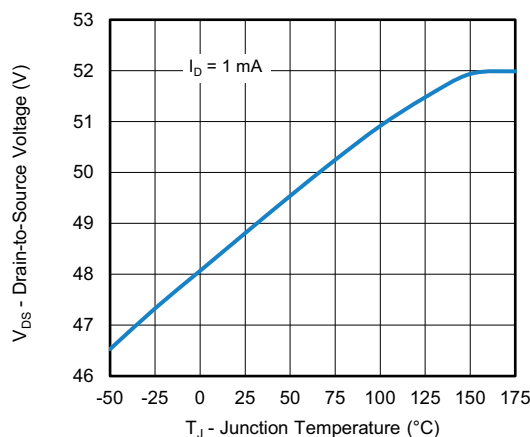
On-Resistance vs. Junction Temperature



Threshold Voltage



On-Resistance vs. Gate-to Source Voltage



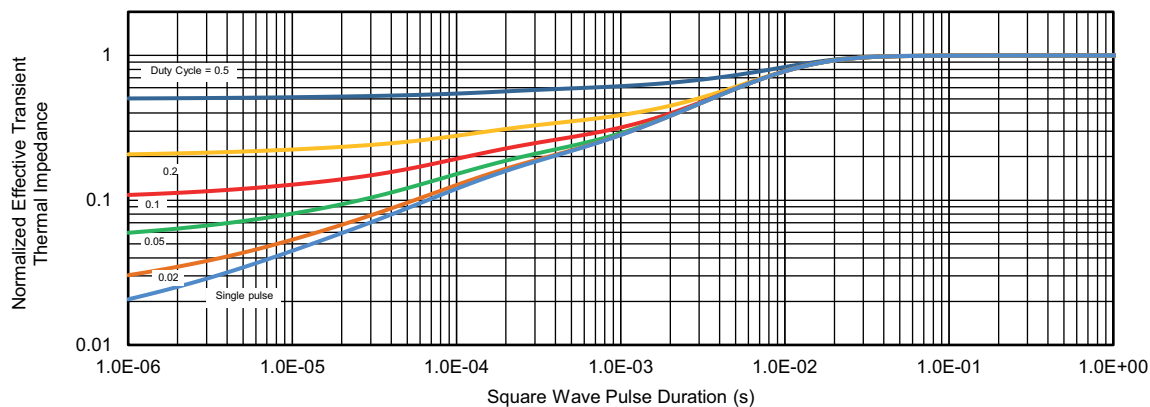
Drain Source Breakdown vs. Junction Temperature

Note

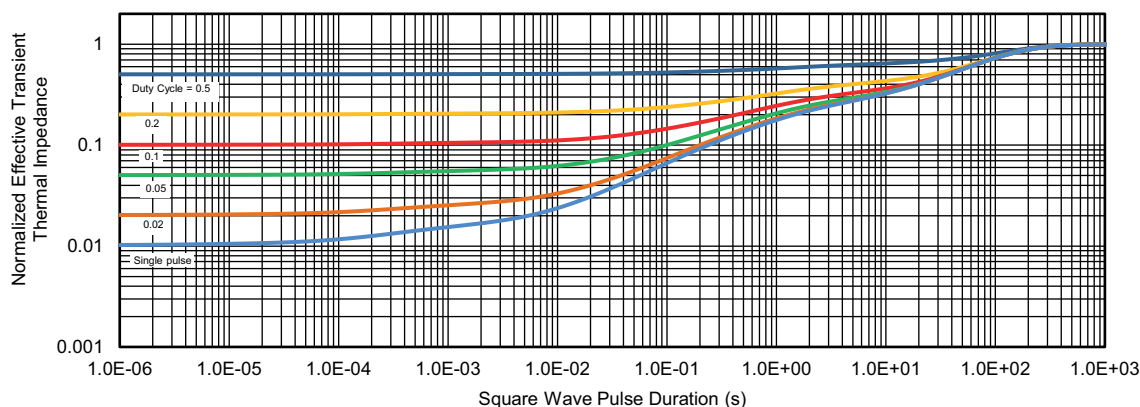
a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case



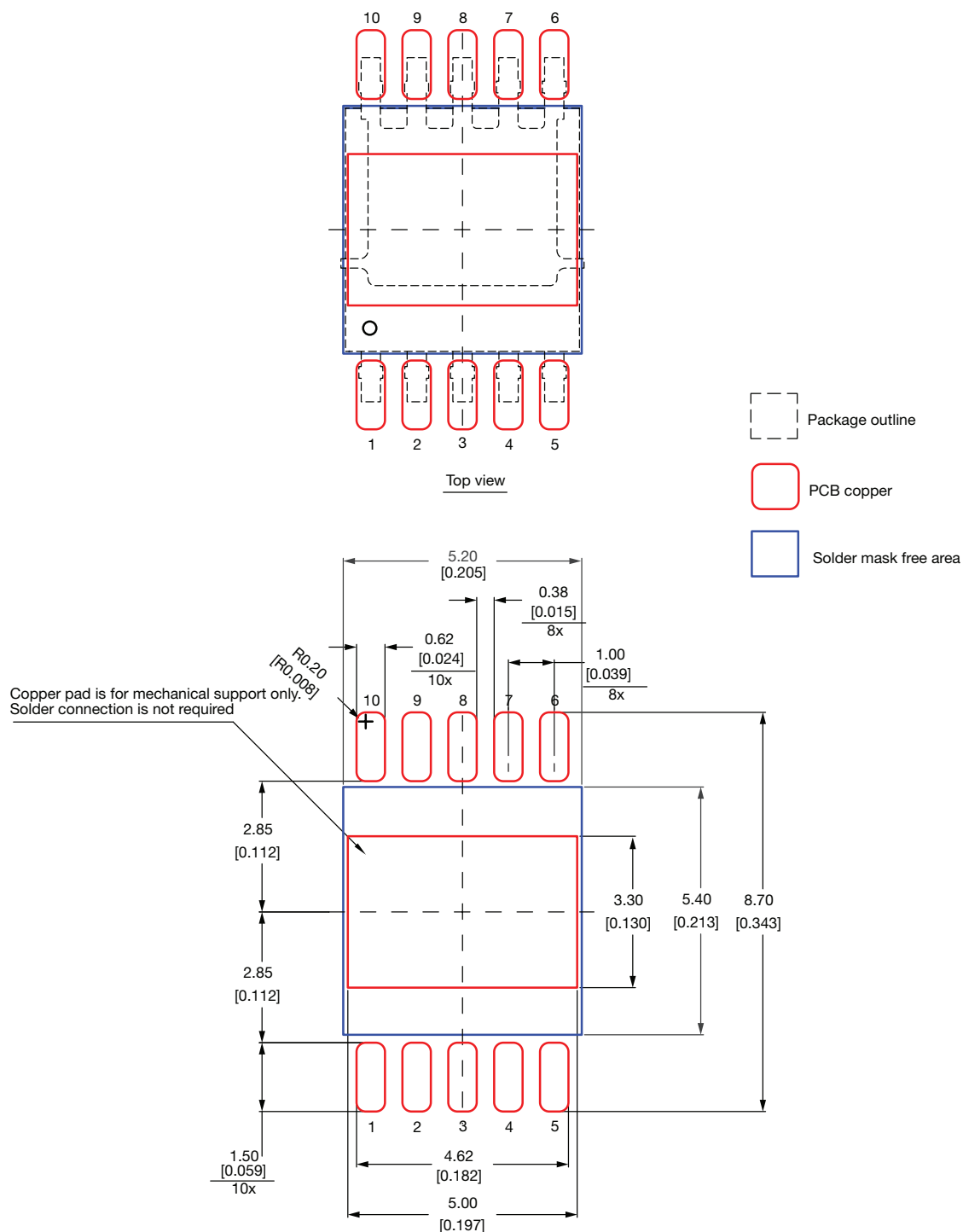
Normalized Thermal Transient Impedance, Junction-to-Ambient

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Case ($25\text{ }^{\circ}\text{C}$)are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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Recommended Land Pattern



Note

- Dimensions in mm [inch]
- This land pattern is for reference

ECN: C23-1310-Rev. A, 11-Dec-2023
DWG: 3021



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